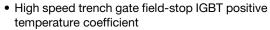


# **Insulated Gate Bipolar Transistor** (Trench IGBT), 600 V, 80 A



PRIMARY CHARACTERISTICS						
V <sub>CES</sub>	600 V					
I <sub>C</sub> DC	80 A at T <sub>C</sub> = 97 °C					
V <sub>CE(on)</sub> typical at 80 A, 25 °C	1.83 V					
I <sub>F (DC)</sub>	56 A at T <sub>C</sub> = 100 °C					
Speed	8 kHz to 30 kHz					
Package	SOT-227					
Circuit configuration	Single switch with AP diode					

#### **FEATURES**





• T<sub>.1</sub> maximum = 175 °C

- FRED Pt® anti-parallel diodes with ultrasoft reverse recovery
- Fully isolated package
- Very low internal inductance (≤ 5 nH typical)
- · Industry standard outline
- UL approved file E78996



· Material categorization: for definitions of compliance please see www.vishav.com/doc?99912

#### **BENEFITS**

- · Designed for increased operating efficiency in power conversion: UPS, SMPS, welding, induction heating
- · Easy to assemble and safe paralleling
- Direct mounting to heatsink
- Plug-in compatible with other SOT-227 packages
- · Lower conduction losses and switching losses
- · Low EMI, requires less snubbing

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
Collector to emitter voltage	V <sub>CES</sub>		600	V
Continuous collector current		T <sub>C</sub> = 25 °C	123	
Continuous collector current	Ic	T <sub>C</sub> = 90 °C	85	]
Pulsed collector current	I <sub>CM</sub>		315	Α
Diode continuous forward current		T <sub>C</sub> = 25 °C	85	
	I <sub>F</sub>	T <sub>C</sub> = 90 °C	60	]
Gate-to-emitter voltage	$V_{GE}$		± 20	V
Device discipation ICDT	В	T <sub>C</sub> = 25 °C	454	
Power dissipation, IGBT	P <sub>D</sub>	T <sub>C</sub> = 90 °C	258	w
Dower discipation diada	В	T <sub>C</sub> = 25 °C	238	] vv
Power dissipation, diode	P <sub>D</sub>	T <sub>C</sub> = 90 °C	135	
Isolation voltage	V <sub>ISOL</sub>	Any terminal to case, t = 1 min	2500	V



<b>ELECTRICAL SPECIFICATIONS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Collector to emitter breakdown voltage	V <sub>BR(CES)</sub>	$V_{GE} = 0 \text{ V}, I_{C} = 2.0 \text{ mA}$	600	-	-	
		$V_{GE} = 15 \text{ V}, I_{C} = 80 \text{ A}$	-	1.83	2.45	
Collector to emitter voltage	V <sub>CE(on)</sub>	$V_{GE} = 15 \text{ V}, I_{C} = 80 \text{ A}, T_{J} = 125 \text{ °C}$	-	2.12	-	V
		$V_{GE} = 15 \text{ V}, I_{C} = 80 \text{ A}, T_{J} = 150^{\circ}\text{C}$	-	2.2	-	
Gate threshold voltage	$V_{GE(th)}$	$V_{CE} = V_{GE}$ , $I_C = 1.0 \text{ mA}$	4.6	5.6	7.5	
Temperature coefficient of threshold voltage	$\Delta V_{GE(th)}/\Delta T_{J}$	$V_{CE} = V_{GE}$ , $I_{C} = 1.0$ mA (25 °C to 150 °C)	-	-18.8	-	mV/°C
		$V_{GE} = 0 \text{ V}, V_{CE} = 600 \text{ V}$	-	0.2	100	
Collector to emitter leakage current	I <sub>CES</sub>	$V_{GE} = 0 \text{ V}, V_{CE} = 600 \text{ V}, T_{J} = 125 ^{\circ}\text{C}$	-	51	-	μΑ
		$V_{GE} = 0 \text{ V}, V_{CE} = 600 \text{ V}, T_{J} = 150 ^{\circ}\text{C}$	-	259	-	
		$I_F = 80 \text{ A}, V_{GE} = 0 \text{ V}$	-	1.92	3.15	
Forward voltage drop, diode	$V_{FM}$	$I_F = 80 \text{ A}, V_{GE} = 0 \text{ V}, T_J = 125  ^{\circ}\text{C}$	-	1.61	-	V
		$I_F = 80 \text{ A}, V_{GE} = 0 \text{ V}, T_J = 150 ^{\circ}\text{C}$	-	1.54	-	
Gate to emitter leakage current	I <sub>GES</sub>	$V_{GE} = \pm 20 \text{ V}$	=.	-	± 250	nA

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Input capacitance	C <sub>iss</sub>			-	10 800	-	
Output capacitance	C <sub>oss</sub>	$V_{GE} = 0 \text{ V}, V_{CE} = 25 \text{ V}, f =$	= 1.0 MHz	-	390	-	рF
Reverse transfer capacitance	C <sub>rss</sub>			-	220	-	
Total gate charge (turn-on)	$Q_g$			-	448	-	
Gate to emitter charge (turn-on)	Q <sub>ge</sub>	$I_C = 80 \text{ A}, V_{CC} = 480 \text{ V}, \text{ V}$	<sub>GE</sub> = 15 V	-	76	-	nC
Gate to collector charge (turn-on)	Q <sub>gc</sub>			-	184	-	
Turn-on switching loss	E <sub>on</sub>			-	1.95	-	
Turn-off switching loss	E <sub>off</sub>			-	1.25	-	mJ
Total switching loss	E <sub>tot</sub>	$I_{\rm C} = 80 \text{ A}, V_{\rm CC} = 300 \text{ V},$	Energy losses include tail and diode recovery.	-	3.2	-	
Turn-on delay time	t <sub>d(on)</sub>	$V_{GE} = 15 \text{ V}, R_g = 27 \Omega,$ $L = 500 \mu\text{H}, T_J = 25 ^{\circ}\text{C}$		-	120	-	ns mJ
Rise time	t <sub>r</sub>			-	90	-	
Turn-off delay time	t <sub>d(off)</sub>			-	442	-	
Fall time	t <sub>f</sub>			-	35	-	
Turn-on switching loss	E <sub>on</sub>	I <sub>C</sub> = 80 A, V <sub>CC</sub> = 300 V,		-	2.3	-	
Turn-off switching loss	E <sub>off</sub>			-	1.43	-	
Total switching loss	E <sub>tot</sub>			-	3.73	-	
Turn-on delay time	t <sub>d(on)</sub>	$V_{GE} = 15 \text{ V}, R_{q} = 27 \Omega,$		-	124	-	
Rise time	t <sub>r</sub>	$L = 500 \mu H, T_J = 125 °C$		-	94	-	
Turn-off delay time	t <sub>d(off)</sub>			-	455	-	ns
Fall time	t <sub>f</sub>			-	43	-	
Diode reverse recovery time	t <sub>rr</sub>	$I_F = 50 \text{ A}, \text{ d}I_F/\text{d}t = 200 \text{ A/}\mu\text{s}, \text{ V}_R = 200 \text{ V}$		-	69	-	ns
Diode peak reverse current	I <sub>rr</sub>			-	4.9	=	Α
Diode recovery charge	Q <sub>rr</sub>			-	169	-	nC
Diode reverse recovery time	t <sub>rr</sub>	I <sub>F</sub> = 50 A, dI <sub>F</sub> /dt = 200 A/μs, V <sub>R</sub> = 200 V, T <sub>J</sub> = 125 °C		-	139	-	ns
Diode peak reverse current	I <sub>rr</sub>			-	12.2	-	Α
Diode recovery charge	Q <sub>rr</sub>			-	856	-	nC



THERMAL AND MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Junction temperature range	TJ		-40	-	175	°C
Storage temperature range	T <sub>Stg</sub>		-40	-	150	°C
Junction-to-case IGBT	В		-	-	0.33	
Diode	R <sub>thJC</sub>		-	-	0.63	°C/W
Case-to-heatsink	R <sub>thCS</sub>	Flat, greased surface		0.1	-	
Weight			-	30	-	g
Mounting torque		Torque to terminal	-	-	1.1 (9.7)	Nm (lbf. in)
Mounting torque		Torque to heatsink	-	-	1.3 (11.5)	Nm (lbf. in)
Case style		S	OT-227			

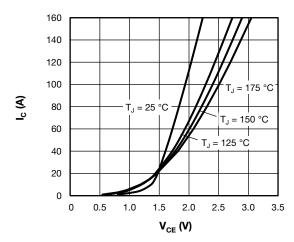


Fig. 1 - Typical IGBT Output Characteristics,  $V_{GE} = 15 \text{ V}$ 

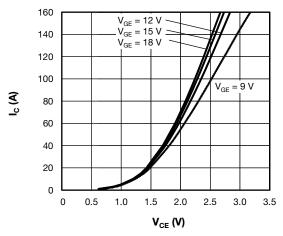


Fig. 2 - Typical IGBT Output Characteristics,  $T_J$  = 125 °C

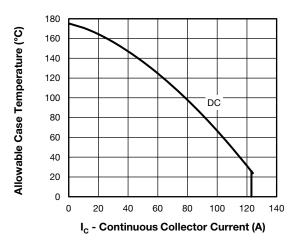


Fig. 3 - Maximum IGBT Continuous Collector Current vs. Case Temperature

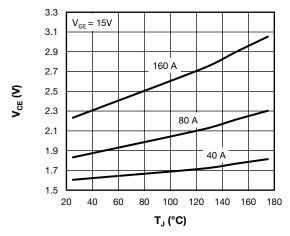


Fig. 4 - Collector to Emitter Voltage vs. Junction Temperature

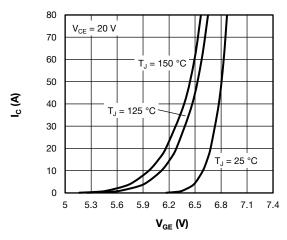


Fig. 5 - Typical IGBT Transfer Characteristics

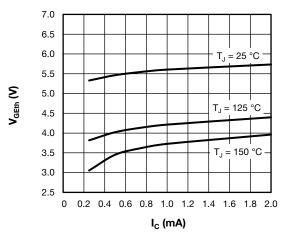


Fig. 6 - Typical IGBT Gate Threshold Voltage

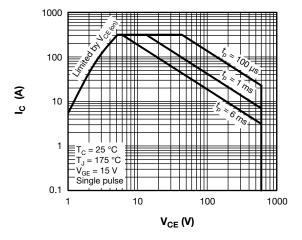


Fig. 7 - IGBT Safe Operating Area

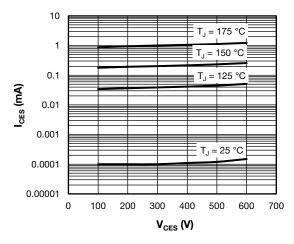


Fig. 8 - Typical IGBT Zero Gate Voltage Collector Current

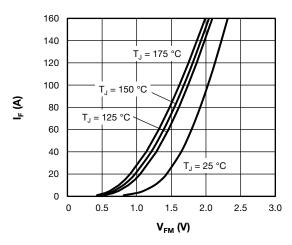


Fig. 9 - Typical Diode Forward Characteristics

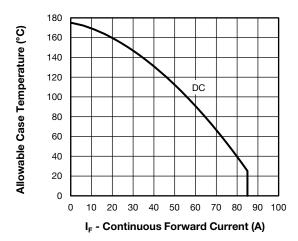


Fig. 10 - Maximum Diode Continuous Forward Current vs. Case Temperature

### www.vishay.com

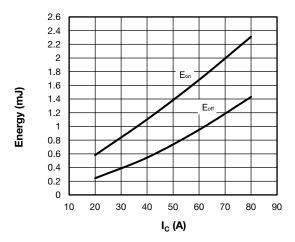


Fig. 11 - Typical IGBT Energy Loss vs. I<sub>C</sub> T<sub>J</sub> = 125 °C, V<sub>CC</sub> = 300 V, R<sub>g</sub> = 27  $\Omega$ , V<sub>GE</sub> = 15 V, L = 500  $\mu$ H

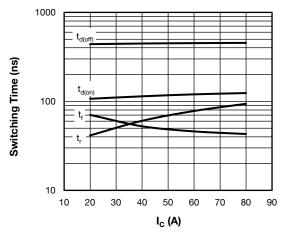


Fig. 12 - Typical IGBT Switching Time vs.  $I_C$  T  $_J$  = 125 °C, V  $_{CC}$  = 300 V, R  $_q$  = 27  $\Omega,$  V  $_{GE}$  = 15 V, L = 500  $\mu H$ 

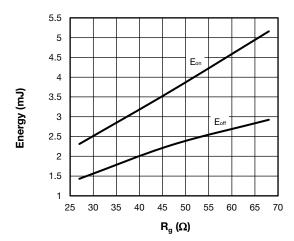


Fig. 13 - Typical IGBT Energy Loss vs.  $R_g$   $T_J$  = 125 °C,  $V_{CC}$  = 300 V,  $I_C$  = 80 A,  $V_{GE}$  = 15 V, L = 500  $\mu H$ 

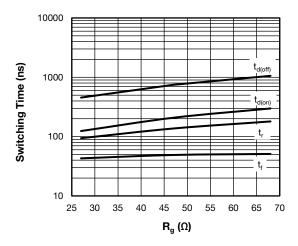


Fig. 14 - Typical IGBT Switching Time vs.  $R_g$   $T_J$  = 125 °C,  $V_{CC}$  = 300 V,  $I_C$  = 80 A,  $V_{GE}$  = 15 V, L = 500  $\mu H$ 

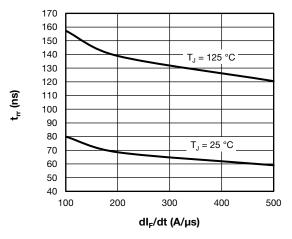


Fig. 15 - Typical  $t_{rr}$  Diode vs.  $dI_F/dt$  $V_{rr} = 200 \text{ V}, I_F = 50 \text{ A}$ 

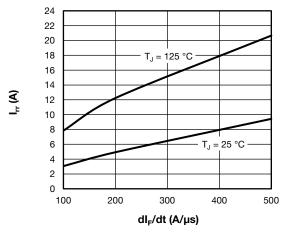


Fig. 16 - Typical  $I_{rr}$  Diode vs.  $dI_F/dt$   $V_{rr} = 200 \text{ V}, I_F = 50 \text{ A}$ 



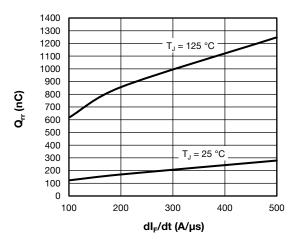


Fig. 17 - Typical Diode Reverse Recovery Charge vs.  $dI_F/dt$   $V_{rr} = 200 \text{ V}, I_F = 50 \text{ A}$ 

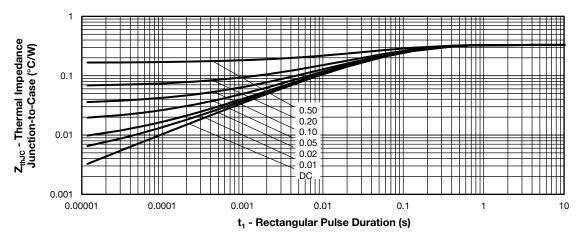


Fig. 18 - Maximum Thermal Impedance Z<sub>thJC</sub> Characteristics, IGBT

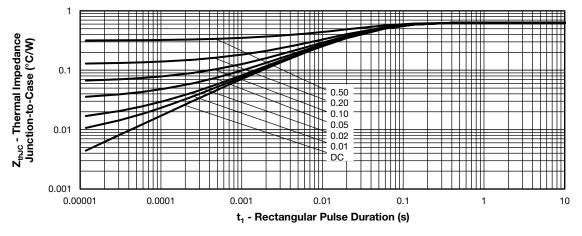
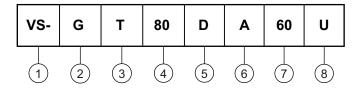


Fig. 19 - Maximum Thermal Impedance  $Z_{\text{thJC}}$  Characteristics, Diode

### **ORDERING INFORMATION TABLE**

Device code



1 - Vishay Semiconductors product

2 - Insulated gate bipolar transistor (IGBT)

T = trench IGBT

**4** - Current rating (80 = 80 A)

- Circuit configuration (D = single switch with antiparallel diode)

6 - Package indicator (A = SOT-227)

7 - Voltage rating (60 = 600 V)

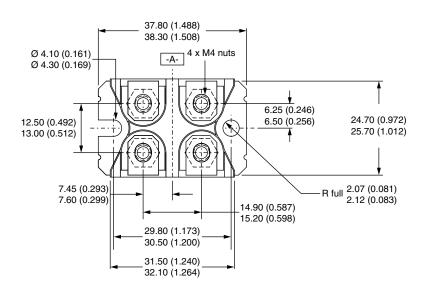
Speed / type (U = ultrafast IGBT)

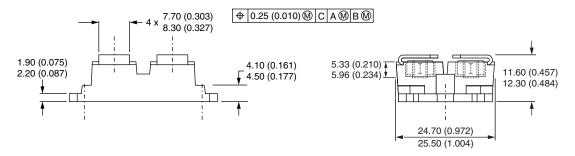
CIRCUIT CONFI	GURATION			
CIRCUIT	CIRCUIT CONFIGURATION CODE	CIRCUIT DRAWING		
Single switch with AP diode	D	Lead Assignment  4  2 (G) 0  1, 4 (E)		

LINKS TO RELATED DOCUMENTS					
Dimensions	www.vishay.com/doc?95423				
Packaging information	www.vishay.com/doc?95425				

### SOT-227 Generation 2

### **DIMENSIONS** in millimeters (inches)





#### Note

· Controlling dimension: millimeter



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